



ESD



TVS



MOS



LDO



Diode



Sensor



DC-DC

## Product Specification

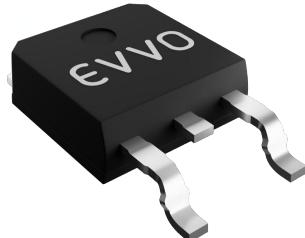
▶ Domestic Part Number	IRFR3710Z
▶ Overseas Part Number	IRFR3710Z
▶ Equivalent Part Number	IRFR3710Z



EV is the abbreviation of name EVVO

**100V N-Channel Enhancement Mode MOSFET****Description**

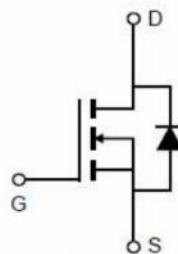
The IRFR3710Z series are from Advanced Power innovative design and silicon process technology to achieve the lowest possible on-resistance and fast switching performance. It provides the designer with an extreme efficient device for use in a wide range of power applications.

**TO-252-2L Pin Configuration****General Features**

$V_{DS} = 100V$   $I_D = 50A$   
 $R_{DS(ON)} < 20 \text{ m}\Omega @ V_{GS}=10V$   
 $R_{DS(ON)} < 27 \text{ m}\Omega @ V_{GS}=4.5V$

**Application**

Battery protection  
Load switch  
Uninterruptible power supply

**Absolute Maximum Ratings** at  $T_j=25^\circ\text{C}$  unless otherwise noted

Parameter	Symbol	Value	Unit
Drain source voltage	$V_{DS}$	100	V
Gate source voltage	$V_{GS}$	$\pm 20$	V
Continuous drain current <sup>1)</sup> , $T_c=25^\circ\text{C}$	$I_D$	50	A
Pulsed drain current <sup>2)</sup> , $T_c=25^\circ\text{C}$	$I_D$ , pulse	120	A
Power dissipation <sup>3)</sup> , $T_c=25^\circ\text{C}$	$P_D$	72	W
Single pulsed avalanche energy <sup>5)</sup>	$E_{AS}$	30	mJ
Operation and storage temperature	$T_{STG}, T_j$	-55 to 150	$^\circ\text{C}$

**Thermal Characteristics**

Parameter	Symbol	Value	Unit
Thermal resistance, junction-case	$R_{\theta JC}$	1.74	$^\circ\text{C}/\text{W}$
Thermal resistance, junction-ambient <sup>4)</sup>	$R_{\theta JA}$	62	$^\circ\text{C}/\text{W}$

**100V N-Channel Enhancement Mode MOSFET****Electrical Characteristics (TA=25°C unless otherwise noted)**

Parameter	Symbol	Test condition	Min.	Typ.	Max.	Unit
Drain-source breakdown voltage	BVDSS	V <sub>GS</sub> =0 V, I <sub>D</sub> =250 μA	100			V
Gate threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250 μA	1.0		2.5	V
Drain-source on-state resistance	R <sub>DSS(ON)</sub>	V <sub>GS</sub> =10 V, I <sub>D</sub> =8 A		16	20	mΩ
Drain-source on-state resistance	R <sub>DSS(ON)</sub>	V <sub>GS</sub> =4.5 V, I <sub>D</sub> =6 A		18	27	mΩ
Gate-source leakage current	I <sub>GSS</sub>	V <sub>GS</sub> =20 V			100	nA
Drain-source leakage current	I <sub>DSS</sub>				-100	
Drain-source leakage current	I <sub>DSS</sub>	V <sub>DS</sub> =100 V, V <sub>GS</sub> =0 V			1	μA
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> =0 V, V <sub>DS</sub> =50 V, f=1 MHz		1190.6		pF
Output capacitance	C <sub>oss</sub>			194.6		pF
Reverse transfer capacitance	C <sub>rss</sub>			4.1		pF
Turn-on delay time	t <sub>d(on)</sub>	V <sub>GS</sub> =10 V, V <sub>DS</sub> =50 V, R <sub>G</sub> =2.2 Ω, I <sub>D</sub> =10 A		17.8		ns
Rise time	t <sub>r</sub>			3.9		ns
Turn-off delay time	t <sub>d(off)</sub>			33.5		ns
Fall time	t <sub>f</sub>			3.2		ns
Total gate charge	Q <sub>g</sub>	I <sub>D</sub> =8 A, V <sub>DS</sub> =50 V, V <sub>GS</sub> =10 V		19.8		nC
Gate-source charge	Q <sub>gs</sub>			2.4		nC
Gate-drain charge	Q <sub>gd</sub>			5.3		nC
Gate plateau voltage	V <sub>plateau</sub>			3.2		V
Diode forward current	I <sub>S</sub>	V <sub>GS</sub> <V <sub>th</sub>			40	A
Pulsed source current	I <sub>SP</sub>				120	A
Diode forward voltage	V <sub>SD</sub>	I <sub>S</sub> =8 A, V <sub>GS</sub> =0 V			1.3	V
Reverse recovery time	t <sub>rr</sub>	I <sub>S</sub> =8 A, di/dt=100 A/μs		50.2		ns
Reverse recovery charge	Q <sub>rr</sub>			95.1		nC
Peak reverse recovery current	I <sub>rrm</sub>			2.5		A

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3) Pd is based on max. junction temperature, using junction-case thermal resistance.
- 4) The value of R<sub>θJA</sub> is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with T<sub>a</sub>=25 °C.
- 5) V<sub>DD</sub>=50 V, R<sub>G</sub>=25 Ω, L=0.3 mH, starting T<sub>j</sub>=25 °C.

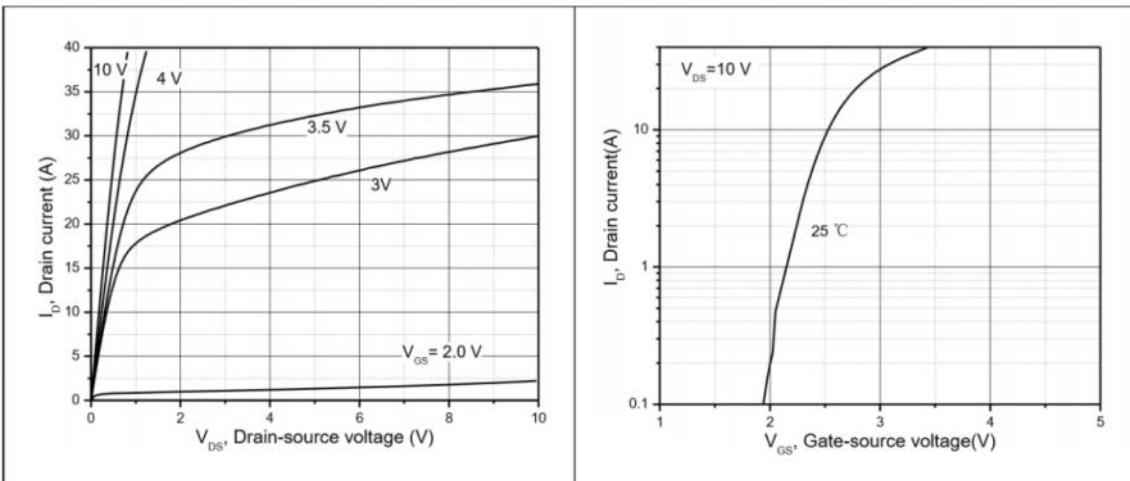
**100V N-Channel Enhancement Mode MOSFET**
**Electrical Characteristics Diagrams**


Figure 1, Typ. output characteristics

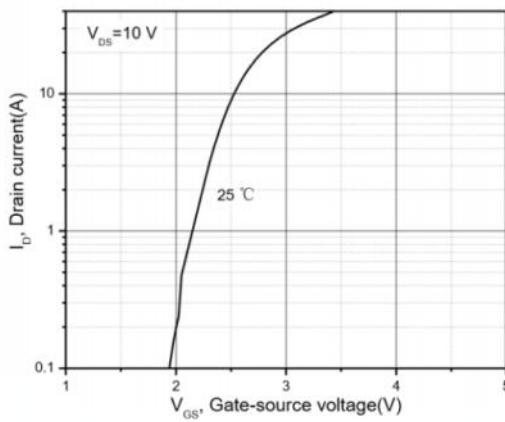


Figure 2, Typ. transfer characteristics

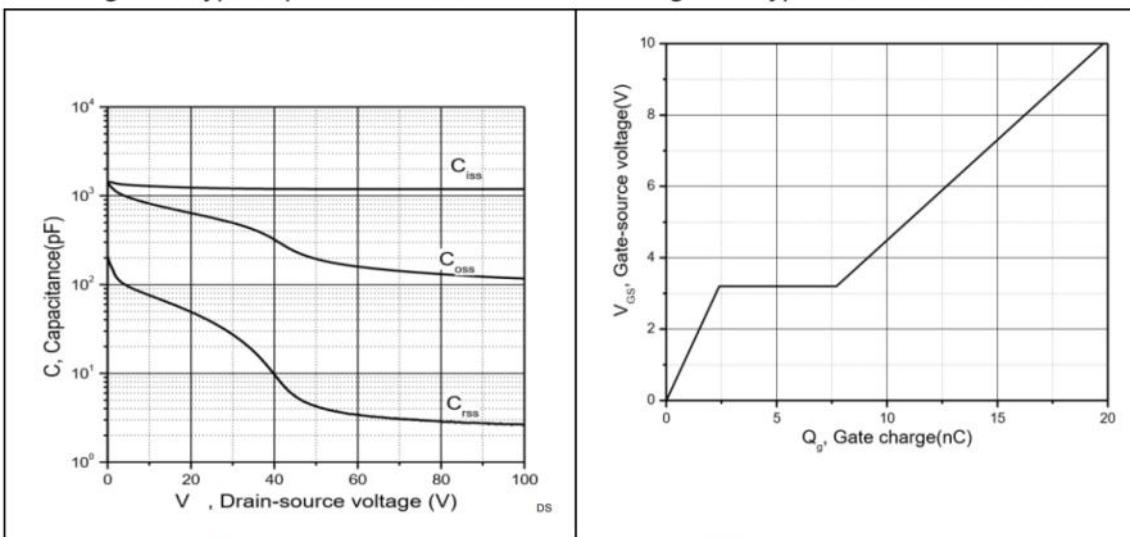


Figure 3, Typ. capacitances

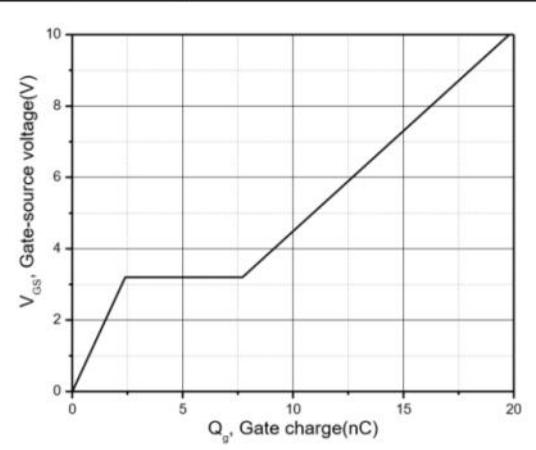


Figure 4, Typ. gate charge

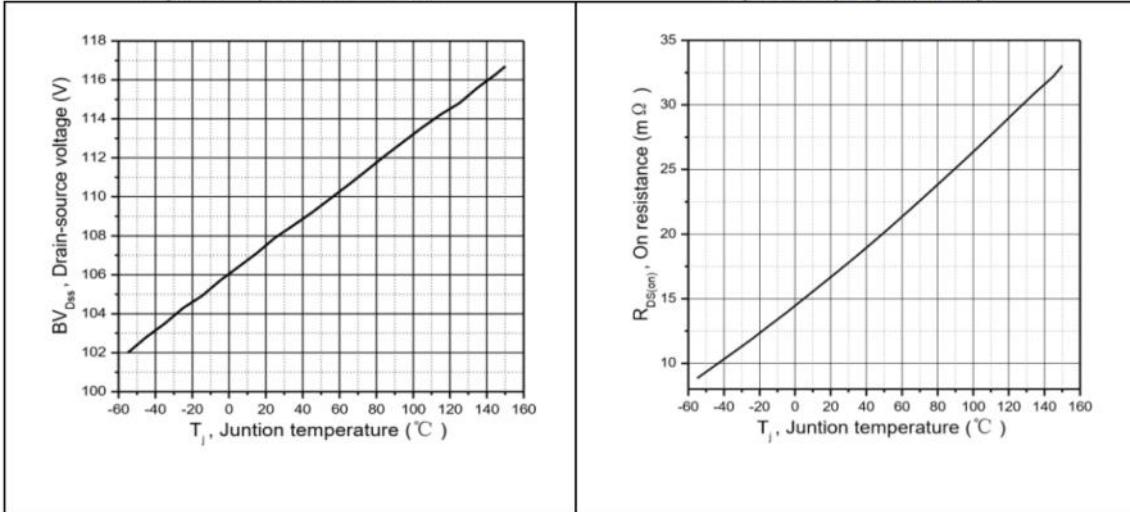


Figure 5, Drain-source breakdown voltage

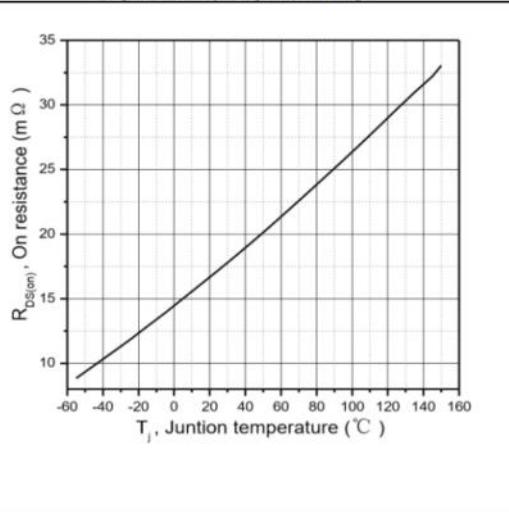


Figure 6, Drain-source on-state resistance

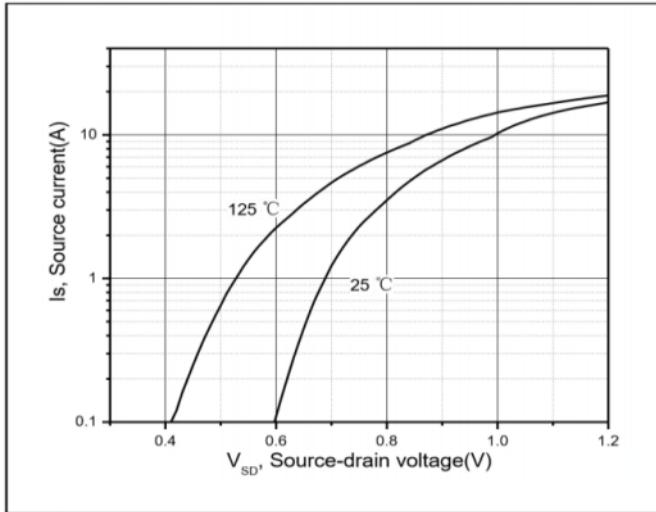
**100V N-Channel Enhancement Mode MOSFET**


Figure 7, Forward characteristic of body diode

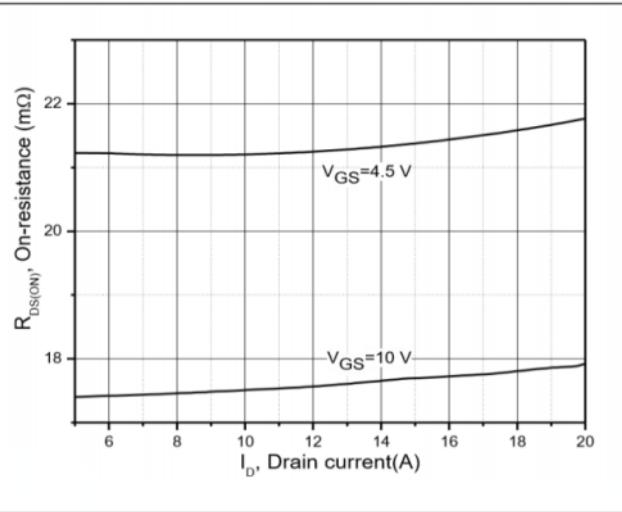
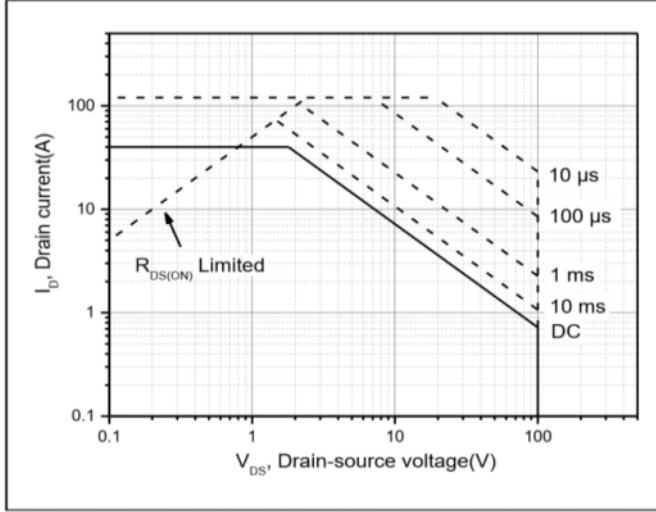


Figure 8, Drain-source on-state resistance

Figure 9, Safe operation area  $T_C=25^\circ\text{C}$

## 100V N-Channel Enhancement Mode MOSFET

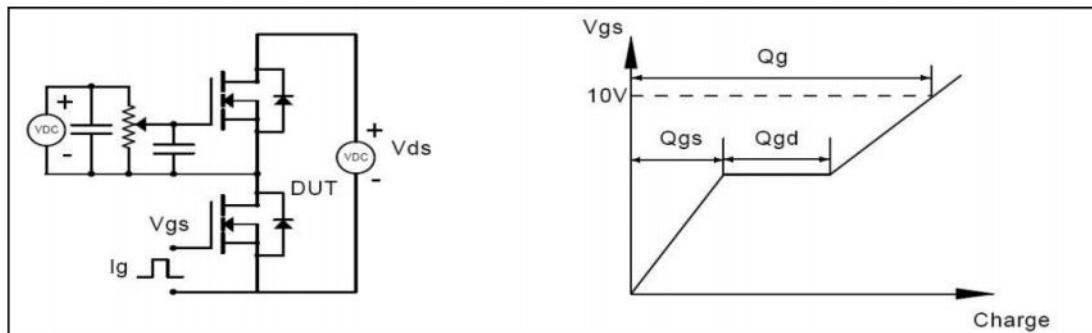


Figure 1, Gate charge test circuit &amp; waveform

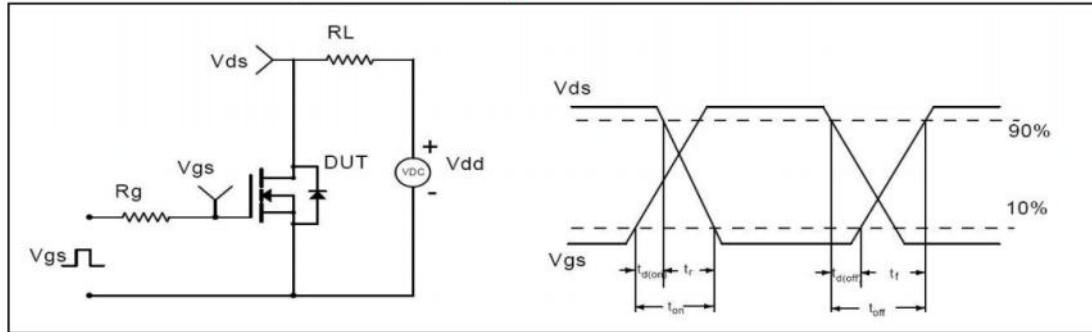


Figure 2, Switching time test circuit &amp; waveforms

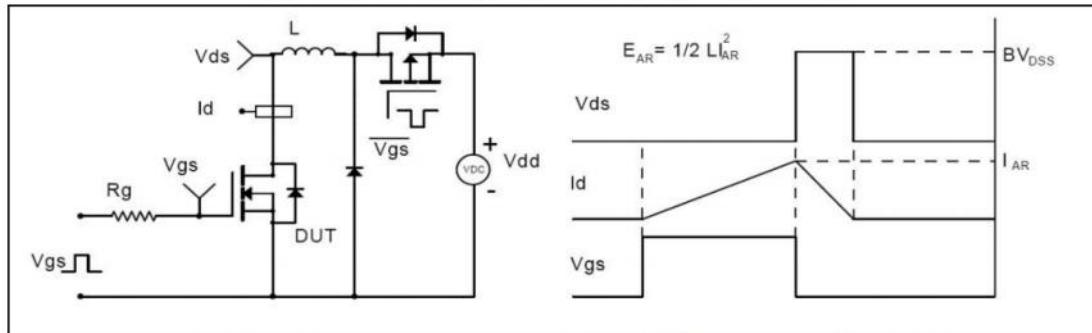


Figure 3, Unclamped inductive switching (UIS) test circuit &amp; waveforms

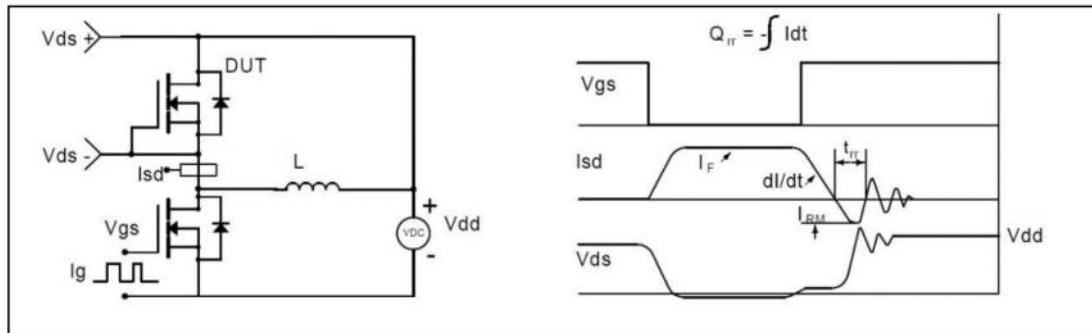
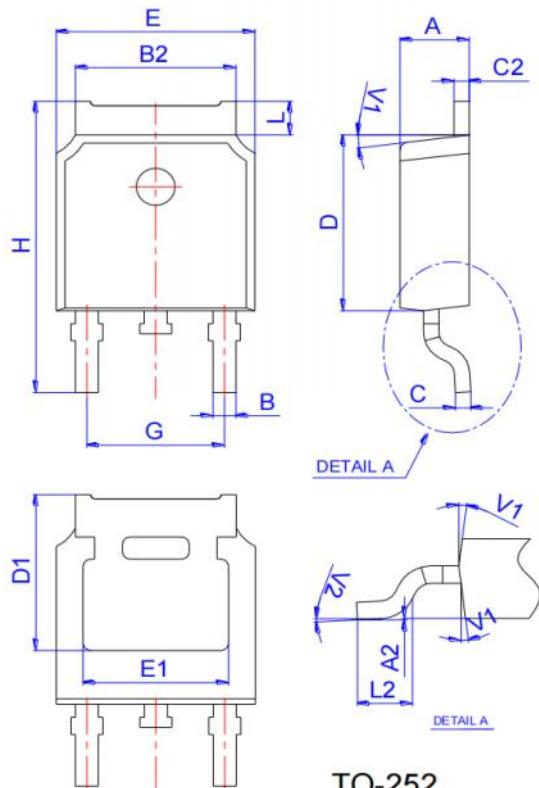
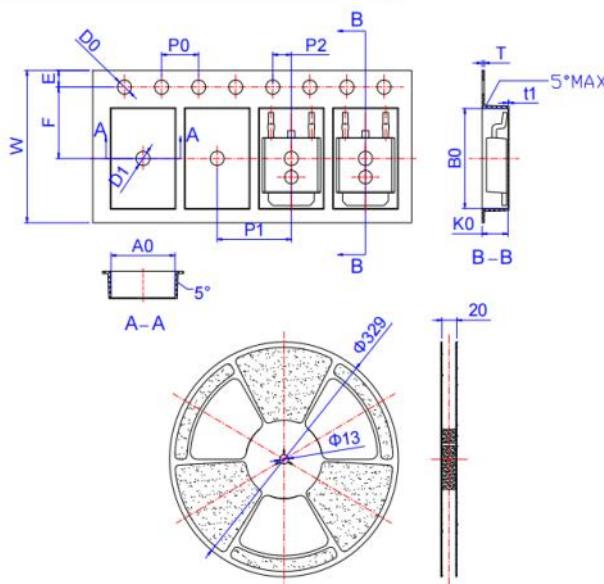


Figure 4, Diode reverse recovery test circuit &amp; waveforms

**100V N-Channel Enhancement Mode MOSFET**
**Package Mechanical Data**


TO-252

Ref.	Dimensions					
	Millimeters			Inches		
Min.	Typ.	Max.	Min.	Typ.	Max.	
A	2.10		2.50	0.083		0.098
A2	0		0.10	0		0.004
B	0.66		0.86	0.026		0.034
B2	5.18		5.48	0.202		0.216
C	0.40		0.60	0.016		0.024
C2	0.44		0.58	0.017		0.023
D	5.90		6.30	0.232		0.248
D1	5.30REF			0.209REF		
E	6.40		6.80	0.252		0.268
E1	4.63			0.182		
G	4.47		4.67	0.176		0.184
H	9.50		10.70	0.374		0.421
L	1.09		1.21	0.043		0.048
L2	1.35		1.65	0.053		0.065
V1		7°			7°	
V2	0°		6°	0°		6°

**Reel Specification-TO-252**


Ref.	Dimensions					
	Millimeters			Inches		
Min.	Typ.	Max.	Min.	Typ.	Max.	
W	15.90	16.00	16.10	0.626	0.630	0.634
E	1.65	1.75	1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291	0.295	0.299
D0	1.40	1.50	1.60	0.055	0.059	0.063
D1	1.40	1.50	1.60	0.055	0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	7.90	8.00	8.10	0.311	0.315	0.319
P2	1.90	2.00	2.10	0.075	0.079	0.083
A0	6.85	6.90	7.00	0.270	0.271	0.276
B0	10.45	10.50	10.60	0.411	0.413	0.417
K0	2.68	2.78	2.88	0.105	0.109	0.113
T	0.24		0.27	0.009		0.011
t1	0.10			0.004		
10P0	39.80	40.00	40.20	1.567	1.575	1.583

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